

RELIABILITY REPORT  
FOR  
MAX6066AEUR+  
PLASTIC ENCAPSULATED DEVICES

November 6, 2009

**MAXIM INTEGRATED PRODUCTS**

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## Conclusion

The MAX6066AEUR+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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### I. Device Description

#### A. General

The MAX6061-MAX6068 are precision, low-dropout, micropower voltage references. These three-terminal devices operate with an input voltage range from ( $V_{OUT} + 50\text{mV}$  typ) to 12.6V and are available with output voltage options of 1.25V, 1.8V, 2.048V, 2.5V, 3V, 4.096V, 4.5V, and 5V. They feature a proprietary curvature-correction circuit and laser-trimmed thin-film resistors that result in a very low temperature coefficient of 20ppm/°C (max) and an initial accuracy of  $\pm 0.2\%$  (max). Specifications apply to the extended temperature range (-40°C to +85°C). The MAX6061-MAX6068 typically draw only 90 $\mu\text{A}$  of supply current and can source 5mA or sink 2mA of load current. Unlike conventional shunt-mode (two-terminal) references that waste supply current and require an external resistor, these devices offer a supply current that is virtually independent of the supply voltage (8 $\mu\text{A/V}$  variation) and do not require an external resistor. Additionally, the internally compensated devices do not require an external compensation capacitor and are stable with up to 1 $\mu\text{F}$  of load capacitance. Eliminating the external compensation capacitor saves valuable board area in space-critical applications. Low dropout voltage and supply independent, ultra-low supply current make these devices ideal for battery-operated, high-performance, low-voltage systems. The MAX6061-MAX6068 are available in a 3-pin SOT23 package.

## II. Manufacturing Information

A. Description/Function:	Precision, Micropower, Low-Dropout, High-Output-Current, SOT23 Voltage References
B. Process:	B12
C. Number of Device Transistors:	
D. Fabrication Location:	Oregon, California or Texas
E. Assembly Location:	Malaysia, Philippines, Thailand
F. Date of Initial Production:	April 22, 2000

## III. Packaging Information

A. Package Type:	3-pin SOT23
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	84-1Imisr4
E. Bondwire:	Au (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-0901-0159
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Jb:	250°C/W
K. Single Layer Theta Jc:	130°C/W

## IV. Die Information

A. Dimensions:	44 X 31 mils
B. Passivation:	Si <sub>3</sub> N <sub>4</sub> /SiO <sub>2</sub> (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	1.2 microns (as drawn)
F. Minimum Metal Spacing:	1.2 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO <sub>2</sub>
I. Die Separation Method:	Wafer Saw

**V. Quality Assurance Information**

- A. Quality Assurance Contacts: Ken Wendel (Director, Reliability Engineering)  
Bryan Preeshl (Managing Director of QA)
- B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.  
0.1% For all Visual Defects.
- C. Observed Outgoing Defect Rate: < 50 ppm
- D. Sampling Plan: Mil-Std-105D

**VI. Reliability Evaluation**

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate ( $\lambda$ ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 160 \times 2} \text{ (Chi square value for MTTF upper limit)}$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 6.71 \times 10^{-9}$$

$$\lambda = 6.71 \text{ F.I.T. (60\% confidence level @ 25°C)}$$

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at <http://www.maxim-ic.com/qa/reliability/monitor>. Cumulative monitor data for the B12 Process results in a FIT Rate of 0.06 @ 25C and 1.06 @ 55C (0.8 eV, 60% UCL)

B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

C. E.S.D. and Latch-Up Testing

The RF24 die type has been found to have all pins able to withstand a HBM transient pulse of +/-2500 V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-250 mA.

**Table 1**  
Reliability Evaluation Test Results

**MAX6066AEUR+**

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
<b>Static Life Test</b> (Note 1)				
	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	160	0
<b>Moisture Testing</b> (Note 2)				
HAST	Ta = 130°C RH = 85% Biased Time = 96hrs.	DC Parameters & functionality	77	0
<b>Mechanical Stress</b> (Note 2)				
Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.

Note 2: Generic Package/Process data